Serial No. : 2013-0679
DATE : 2014/09/30

MediaTek Inc.

ITEM : CRYSTAL RESONATOR

TYPE :	DSR221STH
NOMINAL FREQUENCY :	26.000MHz
SPEC No. :	1RAA26000ABA

Please acknowledge receipt of this specification by signing and returning a copy to us.

RECEIPT	
DATE	
RECEIVED	(signature) (name)

General Manufacturer of Quartz Devices
DAISHINKU CORP.
1389 Shinzaike, Hiraoka-cho, Kakogawa, Hyogo
675-0194 Japan
Phone (81)79-425-3141 Fax (81)79-425-1134
http://www.kds.info/index_en.htm

C.ENG. A. Hishikawa

ENG. H. Takase

Country	Spec No.
TAIWAN	1RAA26000ABA

Device Name Crystal Resonator (with dedicated temperature sensor)
Model Name DSR221STH
Nominal Frequency 26.000 MHz
Mass 0.02g max.
Absolute Maximum Ratings

Item	Rating	unit
Storage Temperature Range	-40~85	°C

Recommended Operating Conditions

Item	min.	typ.	max.	unit
Operating Temperature Range	-30	-	85	°C

1. ELECTRICAL CHARACTERISTICS

Crystal Resonator

(This test shall be performed under the conditions of temp.at 25 ± 3°C, Relative Humidity 60% max.)

	Item	Limits			unit	Conditions	Notes
		min.	typ.	max.			
1	Mode of Vibration	-	AT-cut Fundamental	-			
2	Initial Frequency Tolerance	-	-	±10	ppm	T_A=+25°C	
3	Tolerance Over Temperature	-	-	±10	ppm	T_A= -25~85°C	*1
4	Equivalent Series Resistance	-	-	30	Ω		
5	Spurious Mode Series Resistance	500	-	-	Ω	±1MHz	
6	G Sensitivity	-	-	±2	ppb/G		
7	Full Cycle Temperature Hysteresis	-	-	±0.5	ppm	T_A= -40~85°C	*2
8	Small Cycle Temperature Hysteresis	-	-	±0.05	ppm		*3
9	Load Capacitance	-	7	-	pF		
10	Tuning Sensitivity	25.2	-	30.8	ppm/pF		
11	Insulation Resistance	500	-	-	MΩ		
12	Drive Level	-	-	100	uW		
13	Perturbation	-	-	±0.5	ppm		*4
14	Aging	-	-	±1.0	ppm/year		
		-	-	±1.5	ppm/2years		
		-	-	±2.5	ppm/5years		
		-	-	±5.0	ppm/10years		
15	First-order Curve Fitting Parameter/ C1	-0.15	-0.225	-0.35			*5
16	Second-order Curve Fitting Parameter/ C2	-0.0005	-0.00085	-0.0012			*5
17	Third-order Curve Fitting Parameter/ C3	0.000087	0.000099	0.00011			*5
18	Frequency Stability Slope	-	-	±0.05	ppm	T_A= -10~60°C	*6
		-	-	±0.5	ppm	T_A= -30~85°C	
19	Drive Level Dependency						
	1. Frequency (Max.–Min.)	-	-	2	ppm		*7
	2. Frequency (Repeatability)	-	-	0.7	ppm		*7
	3. ESR (Max.–Min.)	-	-	2.5	Ω		*7
	4. ESR(Repeatability)	-	-	1.5	Ω		*7

Notes

*1. Refer to the value at +25°C

*2. Difference in freq. measurement at any temperature when undergoing a thermal cycle over the entire operation temperature range from -40°C to 85°C per 2°C test

*3. Difference in freq. measurement at any temperature when undergoing a thermal cycle of a temperature range of 5°C per 1°C test

*4. Residual error from the freq. vs. temperature curve fit 5th order. Min. of 1 freq. reading every 3°C over operation temperature

*5. S curve (fL) 3rd order curve fitting coefficient requirement over operation temperature under per 2°C test
[f (T) = C3*(T-T0)^3 + C2*(T-T0)^2 + C1*(T-T0) + C0 ; T0 = 25°C]

*6. Freq. slope error between measured S curve (fL) data and 3rd order curve fitting data over operation temperature under per 2°C test

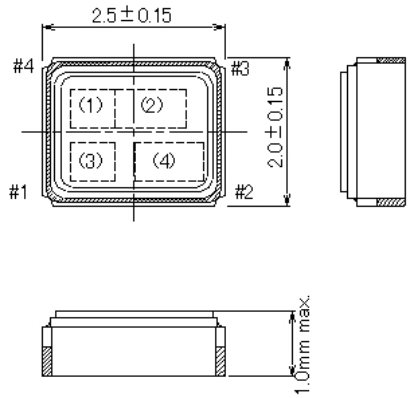
*7. 10nW to 100uW to 10nW

Thermistor

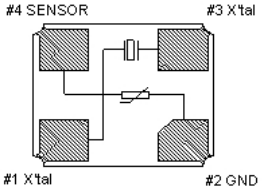
	Item	Limits			unit	Conditions
		min.	typ.	max.		
1	Resistance	-	100	-	kΩ	T_A=+25°C
2	B-constant	-	4250	-	K	+25°C - +50°C

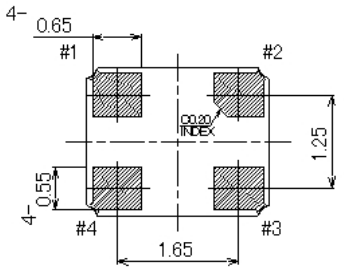
TITLE DSR221STH TYPE QUARTZ CRYSTAL SPECIFICATION	REMARK		
DATE	SPEC. No.	REV.	PAGE
2014/09/30	-		2 / 14

2. DIMENSIONS AND MARKING



Connection (Top View)





Marking

Country	(1) Model code	(2) Frequency (MHz, 3digits)	(3) Logo	(4) Date code
TAIWAN	TH	26.0	• D	Year (1digit) +Week (2digits)
THAILAND	TH	26.0	• D	Year (1digit) +Week (2digits) e.g.2013/1/1→ 301

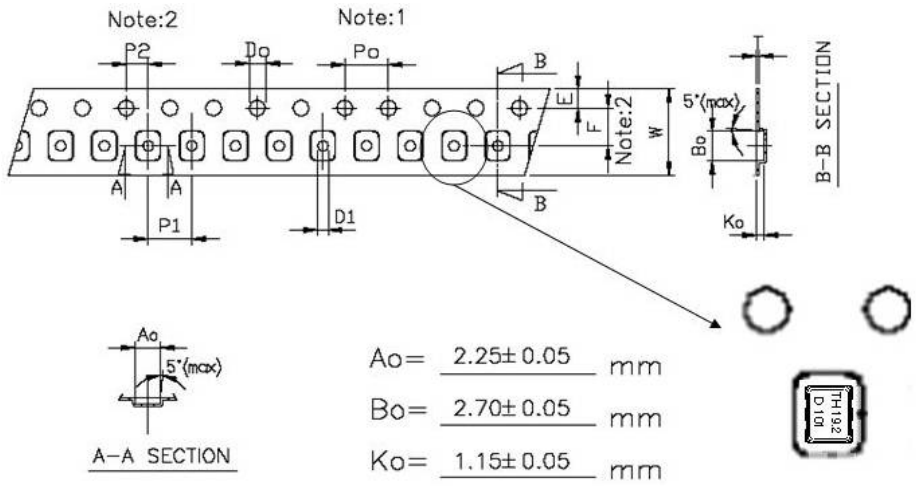
unit:mm general dimension tolerance:0.1mm

Figure-1

TITLE DSR221STH TYPE QUARTZ CRYSTAL SPECIFICATION	REMARK		
DATE	SPEC. No.	REV.	PAGE
2014/09/30	-		3 / 14

3. EMBOSS CARRIER TAPE & REEL

(1) Dimensions of embossed carrier tape



Unit: mm

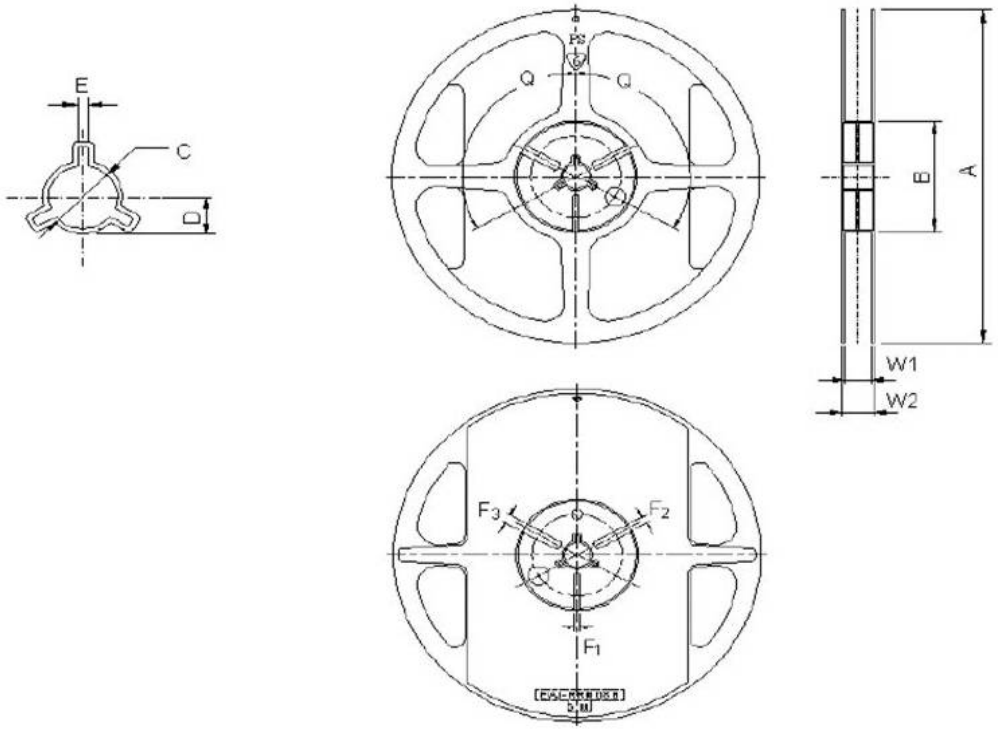
Symbol	Spec.
K1	–
Po	4.0± 0.10
P1	4.0± 0.10
P2	2.0± 0.05
Do	1.55± 0.05
D1	1.10± 0.10
E	1.75± 0.10
F	3.50± 0.05
10Po	40.0± 0.20
W	8.0± 0.20
T	0.25± 0.05

Notice:

1. 10 Sprocket hole pitch cumulative tolerance is ±0.12mm
2. Pocket position relative to sprocket hole measured as true position of pocket not pocket hole.
3. Ao & Bo measured on a place 0.3mm above the bottom of the pocket to top surface of the carrier.
4. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
5. Carrier camber shall be not than 1mm per 100mm through a length of 250mm.

Figure-2

(2) Dimensions of tape reel



ITEM			MARK	DIMENSIONS • ANGLE
FLANCE	Diameter		A	ψ178 +1/-1
	Inner Width		W1	9.0 +/-0.3
	Outer Width		W2	11.5 +/-0.2
HUB	Out Line diameter		B	ψ60 +1.0/-0.0
	Center Core slit	Width	F1	3.0 +0.5/-0
			F2	4.0 +0.5/-0
			F3	5.0 +0.5/-0
		Position	q	120deg
	Spindle diameter		C	ψ13 +/-0.5
	Key Ditch	Width	E	2.5 +0.5/-0
		Periphery	D	11 +/-0.5

Figure-3

TITLE DSR221STH TYPE QUARTZ CRYSTAL SPECIFICATION	REMARK		
DATE	SPEC. No.	REV.	PAGE
2014/09/30	-		5 / 14

(3) Storage condition

Temperature : +40 °C max.
Relative Humidity : 80% max.

(It is a guaranteed term because it obtains an excellent soldering: 1 year)

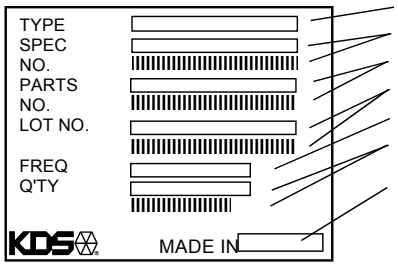
(4) Standard packing quantity

3,000 pcs/reel

(5) Material of the tape

Tape	Material
Carrier tape	Polystyrene (Electrically Conductive)
Cover tape	PET+Olefin resin (Electrically Conductive)
Reel	Polystyrene (Electrically Conductive)

(6) Label contents



Type
Our specification No.
Your Part No.
Lot No.
Nominal Frequency
Quantity
Our Company Name
Producting Country

Stick a label on the each reel.

(7) Taping dimension

Leader	Cover-tape	The length of cover-tape in the leader is more than 400mm including empty embossed area.
	Carrier-tape	After all products were packaged, must remain more than twenty pieces or 400mm empty area, which should be sealed by cover-tape.
Terminal	Cover-tape	The tip of cover-tape shall be fixed temporary by paper tape and roll around the core of reel one round.
	Carrier-tape	The empty embossed area which are sealed by cover-tape must remain more than 40mm.

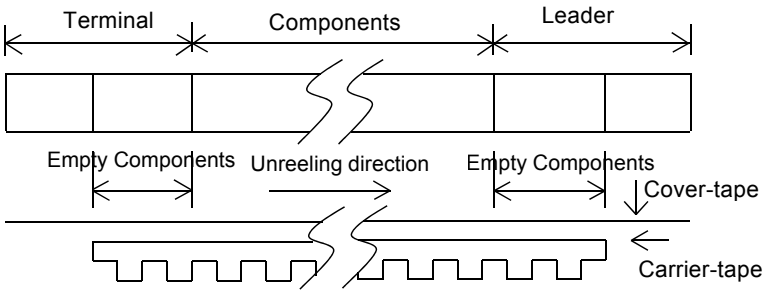


Figure-4

(8) Joint of tape
The carrier-tape and cover-tape should not be jointed.

(9) Release strength of cover tape
It has to between 0.1 ~ 0.7N under following condition.
Pulling direction 165 ~ 180 °
Speed 300mm/min
Otherwise unless specified.

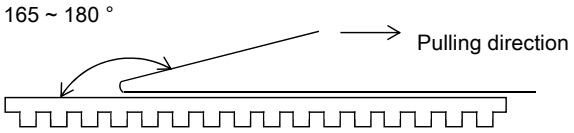
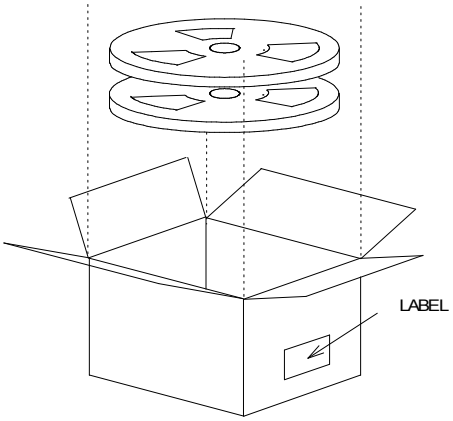


Figure-5

Other standards shall be based on JIS C 0806 -1990.

4. PACKING

(1) STORAGE METHOD



Label contents

The type of product
Lot No.
Specification
Quantity
Shipment Day
Remark

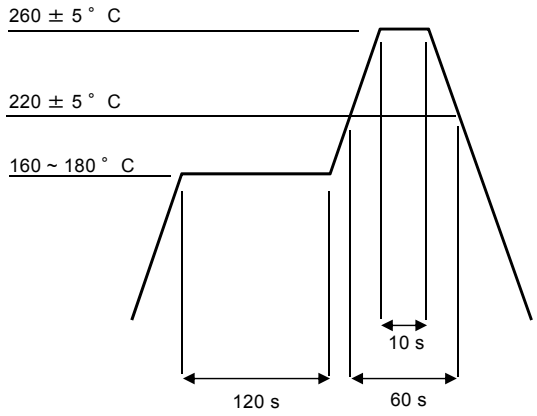
Figure-6

(2) BOX SIZE

From lot size packingsize shall be changed.
In the upper and lower part and the opening in box it shall be protected products using aircushion sheets.

5. REFLOW CONDITIONS (REFERENCE)

During the solder reflow process, please complete within following temperature, period.
Reflow soldering shall be allowed only 3 times.

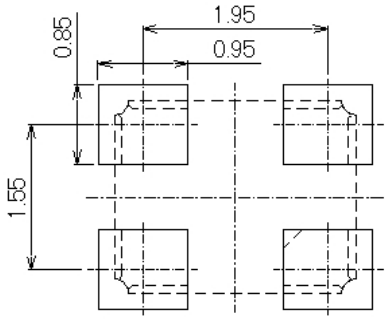


Total time : 240 s max.

Figure-7

HANDSOLDERING METHOD : +350 ± 10 °C , 3+1/-0s Each terminal once
(Please take care so that a soldering iron should not touch a product directly.)

6. LAND PATTERN (REFERENCE)



unit : mm

Figure-8

TITLE DSR221STH TYPE QUARTZ CRYSTAL SPECIFICATION	REMARK		
DATE	SPEC. No.	REV.	PAGE
2014/09/30	-		9 / 14

7. MECHANICAL ENDURANCE

(1) SHOCK (ACCELERATION)
After the following test,parts shall conform specification 9.A
1000m/s^2 by 6ms X,Y,Z each axis (6 directions) , 3cycles

(2) SHOCK (MOUNTING DROP)
After the following test,parts shall conform specification 9.A
3cycles(18times) drop from 150 cm heights to concrete.
Further,parts shall be solderd on substrate, fixed Aluminum materials(about 100g).

Substrate materials	:	Glass Epoxy
1 cycle	:	each 1 times of 6 directions

(3) VIBRATION
After the following test,parts shall conform specification 9.A
and no abnormal appearance shall be observed.

Frequency of Vibration	:	10 ~ 500 ~ 10 Hz
Amplitude(p-p)	:	Sine waves of 1.5mm or 100m/s^2
Cycle	:	11min
Vibration axis	:	X.Y.Z
Vibration period	:	2 h for each axis

(4) SEAL
Less than 2.0×10^{-9} Pa m^3/s. by Helium leak detector.
Also, no serial bubble is observed by Fluorocarbon tests.

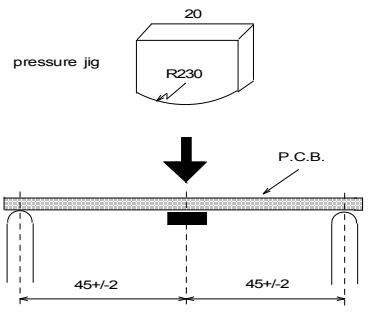
(5) SOLDERABILITY
After the following test, more than 95% of terminal shall be covered by new solder.
3 ± 0.5 s dip in +245 ± 5 °C solder.
(Solder composition : Sn-3Ag-0.5Cu) (Use rosin type flux for solder.)

(6) RESISTANCE TO SOLDERING HEAT (REFLOW)
48 h past at room temperature from following test,parts shall conform specification 9.A
perform the attached Reflow conditions to reference.

(7) RESISTANCE TO SOLDERING HEAT (HAND SOLDERING METHOD)
48 h past at room temperature from following test,parts shall conform specification 9.A
+350 ± 10°C , 3+1/-0s Each terminal once.

(8) SUBSTRATE BENDING
After the following test,parts shall conform specification 9.A
and no abnormality shall be observed in external appearance and sealing
tightnen and others shall be based on ET-7403 of EIAJ.
Mount the specimen on substrate.
Apply the following pressure

Direction	:	see right figure
Speed	:	about 1.0 mm/s
Hours	:	5 ± 1 s
Amount of substrate	:	3 mm max.

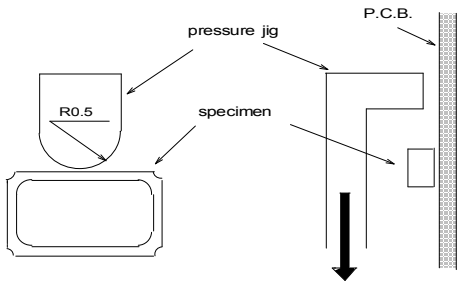


(9) SHEAR

After the following test,parts shall conform specification 9.A
and no abnormality shall be observed in external appearance and sealing
tightness and others shall be based on ET-7403 of EIAJ.

Mount the specimen on substrate.
Apply the following pressure

Weight	:	10 N
Hours	:	10 ± 1 s
Direction	:	see right figure

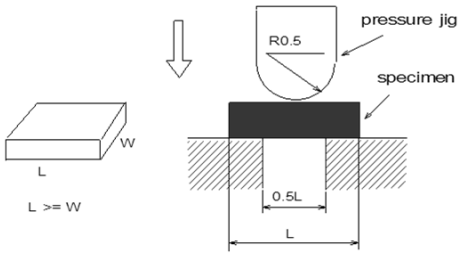


(10) BODY STRENGTH

After the following test,parts shall conform specification 9.A
and no abnormality shall be observed in external appearance and sealing
tightness and others shall be based on ET-7403 of EIAJ.

Mount the specimen on substrate.
Apply the following pressure

Weight	:	5N
Hours	:	10 ± 1 s
Direction	:	see right figure



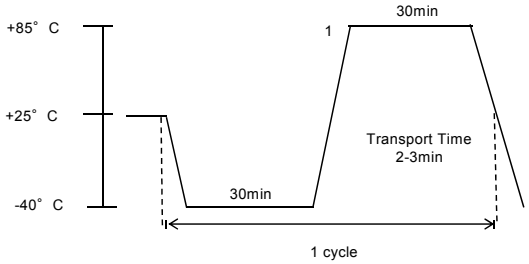
8. ENVIRONMENTAL ENDURANCE

(1) LOW TEMPERATURE
2 h past at room temperature after following test, parts shall conform specification 9.A
240 h , -40 ± 3 °C.

(2) HUMIDITY
2 h past at room temperature after following test, parts shall conform specification 9.A
240 h , +85 ± 2 °C , relative humidity 85 ± 5%.

(3) HIGH TEMPERATURE
2 h past at room temperature after following test, parts shall conform specification 9.A
240 h , +85 ± 2 °C.

(4) TEMPERATURE CYCLE
2 h past at room temperature after 1000 cycles of followingtest, parts shall conform specification 9.A



9. SPECIFICATION

Frequency Variation and Equivalent Resistance shall be within Table below after the reliability test.

Spec.	Frequency Variation	Equivalent Resistance
A	±2ppm	±15 % or 2.0 Ω max. (Use larger specification)
B	±5ppm	±20 % or 3.0 Ω max. (Use larger specification)
C	±10ppm	±20 % or 3.0 Ω max. (Use larger specification)
D	±20ppm	±25 % or 10.0 Ω max. (Use larger specification)

10. DSR221STH TYPE QUARTZ CRYSTAL HANDLING INSTRUCTIONS

(1) SOLDERING

Please perform the attached Reflow conditions to reference within 3 times.

(2) MOUNT

Crystal products are designed to be compatible with automatic mounting.
Be sure to have a mounting test in advance by using the actual mounting machine and check that the characteristics of the products are not damaged by the automatic mounting.
In the process where the boad is warped, such as board separation process, be careful that the warping does not influence the characteristics and soldering of crystal products.
Since mounting by Ultrasonic welding and processing have a possibility of an excessive vibration spreading inside a crystal resonator and becoming the cause of characteristic deterioration and not oscillating, it does not recommend.

(3) WASHING

About use of the washing liquid of a basin system, an alcoholic system, and a chlorofluorocarbon-replacing material system, it is checking that it is satisfactory.
However please consult in advance about other washing liquid.
Although the check about ultrasonic washing is performed, since it is an examination with a simple substance, the check for the second time by the use state is recommended.

(4) THE CAUTIONS ON USE

The piece of crystal it is processed very smaller than the conventional thing inside DSR221STH series crystal unit may be damaged, if excessive excitation electric power is applied.
Please use it below with the value specified on a catalog and specifications.
Please refrain from forming patterns between crystal land pattern's since there is a possibility to cause crack in base.

(5) HANDLING OF A PRODUCT

DSR221STH series has sufficient intensity to fall and vibration.
However when too much shock is added according to a certain cause, the use after a characteristic check is recommended.

(6) STORAGE

Since the soldering nature of a terminal may be degraded, please avoid storage in high temperature and a humid place.
Please keep it in the place which direct rays do not hit and dew condensation does not generate.

2013-0679 REVISION RECORD

Rev.No	Date	Reason	Contents	Approved	Checked	Drawn
-	2014/09/30	-	Initial Release	A.Hishikawa	H.Takase	H.Takase